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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	52
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 20x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/atsamd20j14a-au">https://www.e-xfl.com/product-detail/microchip-technology/atsamd20j14a-au</a>

## 2. Configuration Summary

	SAM D20J	SAM D20G	SAM D20E
Pins	64	48	32
General Purpose I/O-pins (GPIOs)	52	38	26
Flash	256/128/64/32KB	256/128/64/32KB	256/128/64/32KB
SRAM	32/16/8/4/2KB	32/16/8/4/2KB	32/16/8/4/2KB
Timer Counter (TC) instances	8	6	6
Waveform output channels per TC instance	2	2	2
Serial Communication Interface (SERCOM) instances	6	6	4
Analog-to-Digital Converter (ADC) channels	20	14	10
Analog Comparators (AC)	2	2	2
Digital-to-Analog Converter (DAC) channels	1	1	1
Real-Time Counter (RTC)	Yes	Yes	Yes
RTC alarms	1	1	1
RTC compare values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values	One 32-bit value or two 16-bit values
External Interrupt lines	16	16	16
Peripheral Touch Controller (PTC) X and Y lines	16x16	12x10	10x6
Maximum CPU frequency	48MHz		
Packages	QFN TQFP UFBGA	QFN TQFP WLCSP	QFN TQFP
Oscillators	32.768kHz crystal oscillator (XOSC32K) 0.4-32MHz crystal oscillator (XOSC) 32.768kHz internal oscillator (OSC32K) 32KHz ultra-low-power internal oscillator (OSCULP32K) 8MHz high-accuracy internal oscillator (OSC8M) 48MHz Digital Frequency Locked Loop (DFLL48M)		
Event System channels	8	8	8
SW Debug Interface	Yes	Yes	Yes
Watchdog Timer (WDT)	Yes	Yes	Yes

### 3.2. SAM D20G

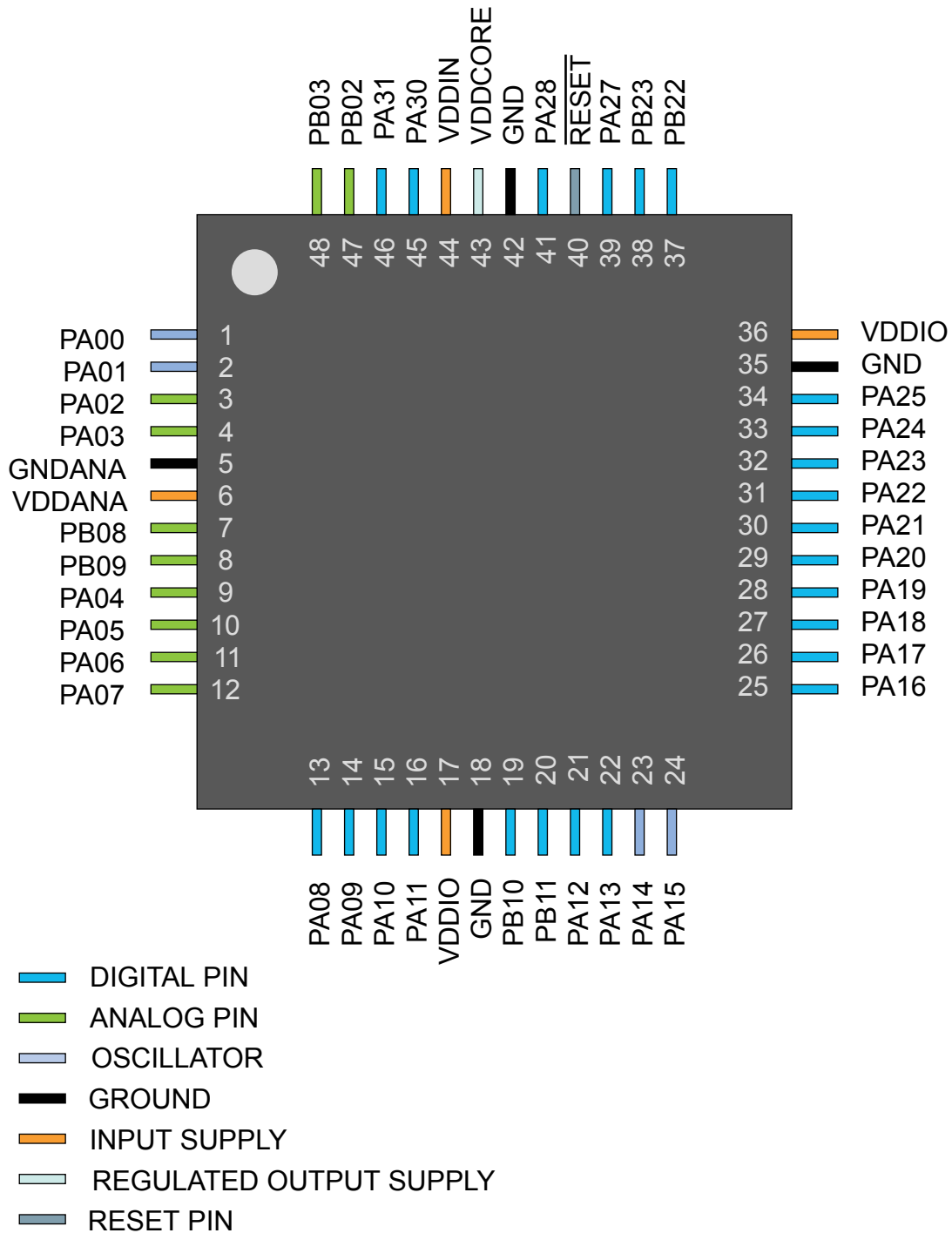
Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20G14A-AU	16K	2K	TQFP32	Tray
ATSAMD20G14A-AUT				Tape & Reel
ATSAMD20G14A-AN				Tray
ATSAMD20G14A-ANT				Tape & Reel
ATSAMD20G14A-MU			QFN32	Tray
ATSAMD20G14A-MUT				Tape & Reel
ATSAMD20G14A-MN				Tray
ATSAMD20G14A-MNT				Tape & Reel
ATSAMD20G15A-AU	32K	4K	TQFP48	Tray
ATSAMD20G15A-AUT				Tape & Reel
ATSAMD20G15A-AN				Tray
ATSAMD20G15A-ANT				Tape & Reel
ATSAMD20G15A-MU			QFN48	Tray
ATSAMD20G15A-MUT				Tape & Reel
ATSAMD20G15A-MN				Tray
ATSAMD20G15A-MNT				Tape & Reel
ATSAMD20G16A-AU	64K	8K	TQFP48	Tray
ATSAMD20G16A-AUT				Tape & Reel
ATSAMD20G16A-AN				Tray
ATSAMD20G16A-ANT				Tape & Reel
ATSAMD20G16A-MU			QFN48	Tray
ATSAMD20G16A-MUT				Tape & Reel
ATSAMD20G16A-MN				Tray
ATSAMD20G16A-MNT				Tape & Reel

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20E14A	0x0E	0x1000130E
Reserved	0x0F	
SAMD20G18U	0x10	0x10001310
SAMD20G17U	0x11	0x10001311
Reserved	0x12 - 0xFF	

**Note:** The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

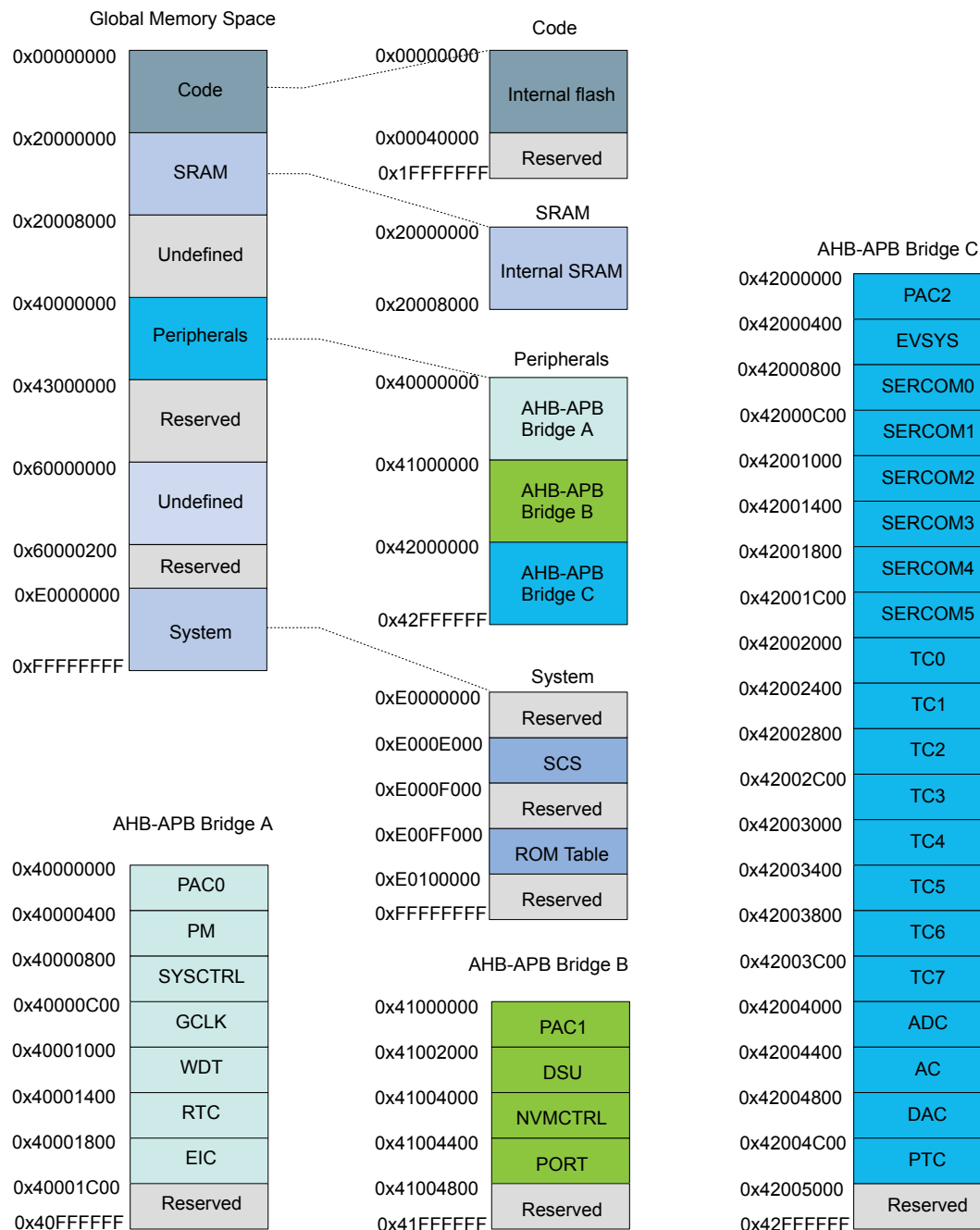
## 5.2. SAM D20G

### 5.2.1. QFN48 / TQFP48



## 6. Product Mapping

Figure 6-1. Product Mapping



This figure represents the full configuration of the SAM D20 device with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the [Configuration Summary](#) for details.

## 7. Processor And Architecture

### 7.1. Cortex M0+ Processor

The SAM D20 implements the ARM® Cortex®-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The ARM Cortex-M0+ implemented is revision r0p1. For more information refer to <http://www.arm.com>.

#### 7.1.1. Cortex M0+ Configuration

Table 7-1. Cortex M0+ Configuration

Features	Configurable option	Device configuration
Interrupts	External interrupts 0-32	28
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent <sup>(1)</sup>
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

**Note:**

1. All software run in privileged mode only.

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
- Single 32-bit I/O port bus interfacing to the PORT with 1-cycle loads and stores.

#### 7.1.2. Cortex-M0+ Peripherals

- System Control Space (SCS)
  - The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details ([www.arm.com](http://www.arm.com)).
- System Timer (SysTick)

Peripheral Source	NVIC Line
DAC – Digital-to-Analog Converter	23
PTC – Peripheral Touch Controller	24

## 7.3. Micro Trace Buffer

### 7.3.1. Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

### 7.3.2. Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

## 7.4. High-Speed Bus System

### 7.4.1. Features

High-Speed Bus Matrix has the following features:

- Symmetric crossbar bus switch implementation
- Allows concurrent accesses from different masters to different slaves
- 32-bit data bus
- Operation at a one-to-one clock frequency with the bus masters

### 7.4.2. Configuration

**Table 7-4. Bus Matrix Masters**

Bus Matrix Masters	Master ID
CM0+ - Cortex M0+ Processor	0
DSU - Device Service Unit	1

**Table 7-5. Bus Matrix Slaves**

Bus Matrix Slaves	Slave ID
Internal Flash Memory	0
AHB-APB Bridge A	1
AHB-APB Bridge B	2
AHB-APB Bridge C	3

## 7.5. AHB-APB Bridge

The AHB-APB bridge is an AHB slave, providing an interface between the high-speed AHB domain and the low-power APB domain. It is used to provide access to the programmable control registers of peripherals (see *Product Mapping*).

AHB-APB bridge is based on AMBA APB Protocol Specification V2.0 (ref. as APB4) including:

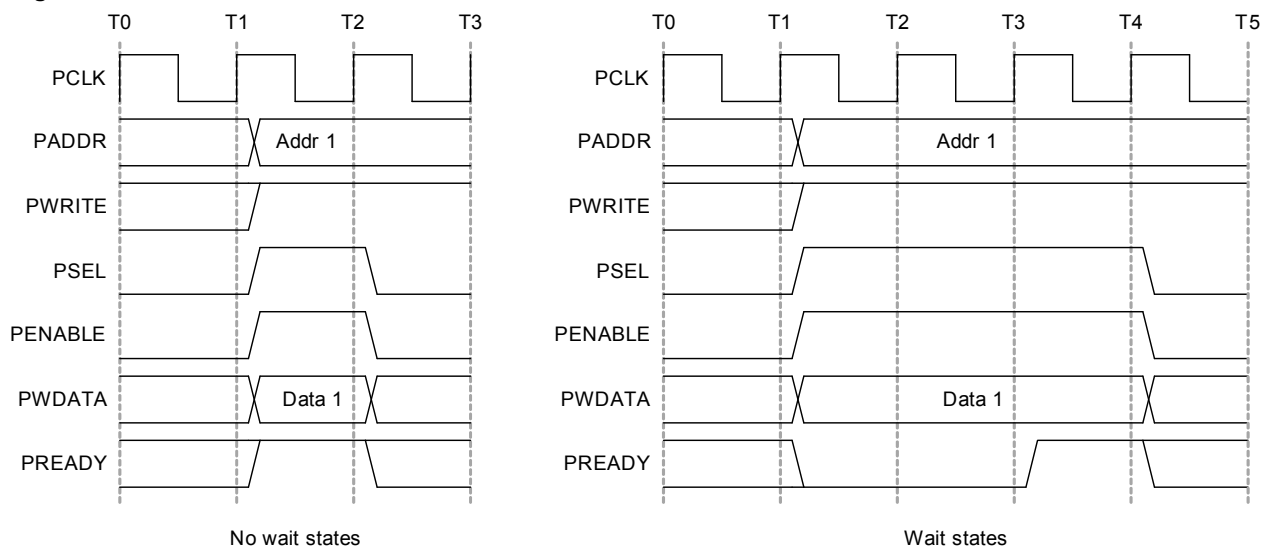
- Wait state support
- Error reporting
- Transaction protection
- Sparse data transfer (byte, half-word and word)

Additional enhancements:

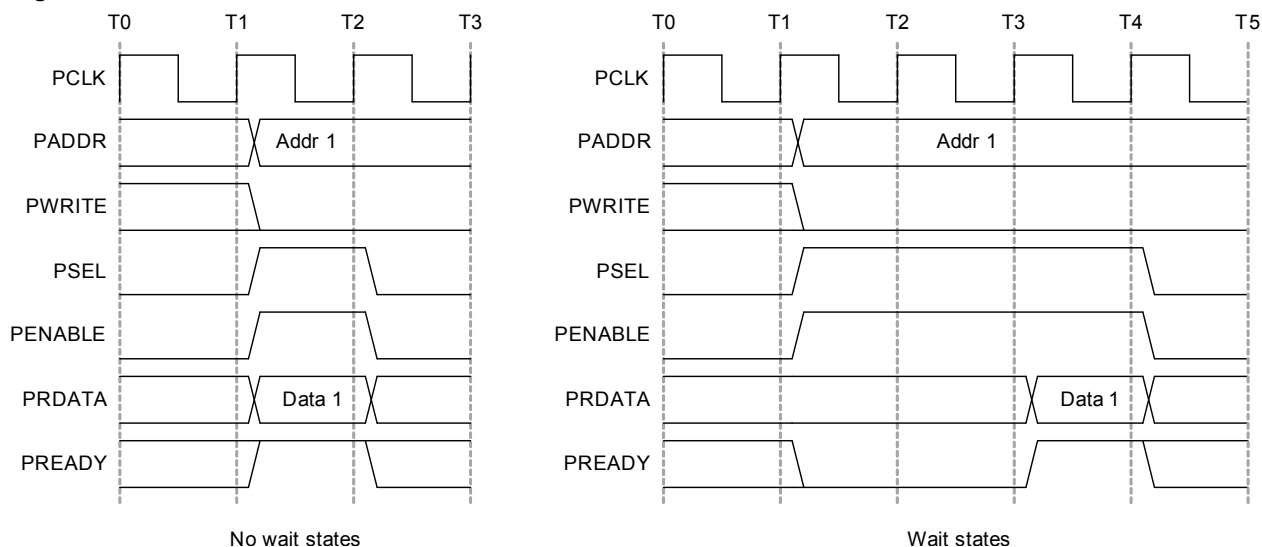
- Address and data cycles merged into a single cycle
- Sparse data transfer also apply to read access

to operate the AHB-APB bridge, the clock (CLK\_HPBB\_AHB) must be enabled. See *PM – Power Manager* for details.

**Figure 7-1. APB Write Access.**



**Figure 7-2. APB Read Access.**



## Related Links

[Product Mapping](#) on page 19

## 7.6. PAC - Peripheral Access Controller

### 7.6.1. Overview

There is one PAC associated with each AHB-APB bridge. The PAC can provide write protection for registers of each peripheral connected on the same bridge.

The PAC peripheral bus clock (CLK\_PACx\_APB) can be enabled and disabled in the Power Manager. CLK\_PAC0\_APB and CLK\_PAC1\_APB are enabled at reset. CLK\_PAC2\_APB is disabled at reset. Refer to *PM – Power Manager* for details. The PAC will continue to operate in any sleep mode where the selected clock source is running. Write-protection does not apply for debugger access. When the debugger makes an access to a peripheral, write-protection is ignored so that the debugger can update the register.

### 7.7.1.1. Write Protect Clear

**Name:** WPCLR  
**Offset:** 0x00  
**Reset:** 0x000000  
**Property:** –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								
Bit	23	22	21	20	19	18	17	16
Access								
Reset								
Bit	15	14	13	12	11	10	9	8
Access								
Reset								
Bit	7	6	5	4	3	2	1	0
		EIC	RTC	WDT	GCLK	SYSCTRL	PM	
Access		R/W	R/W	R/W	R/W	R/W	R/W	
Reset		0	0	0	0	0	0	

#### Bit 6 – EIC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 5 – RTC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

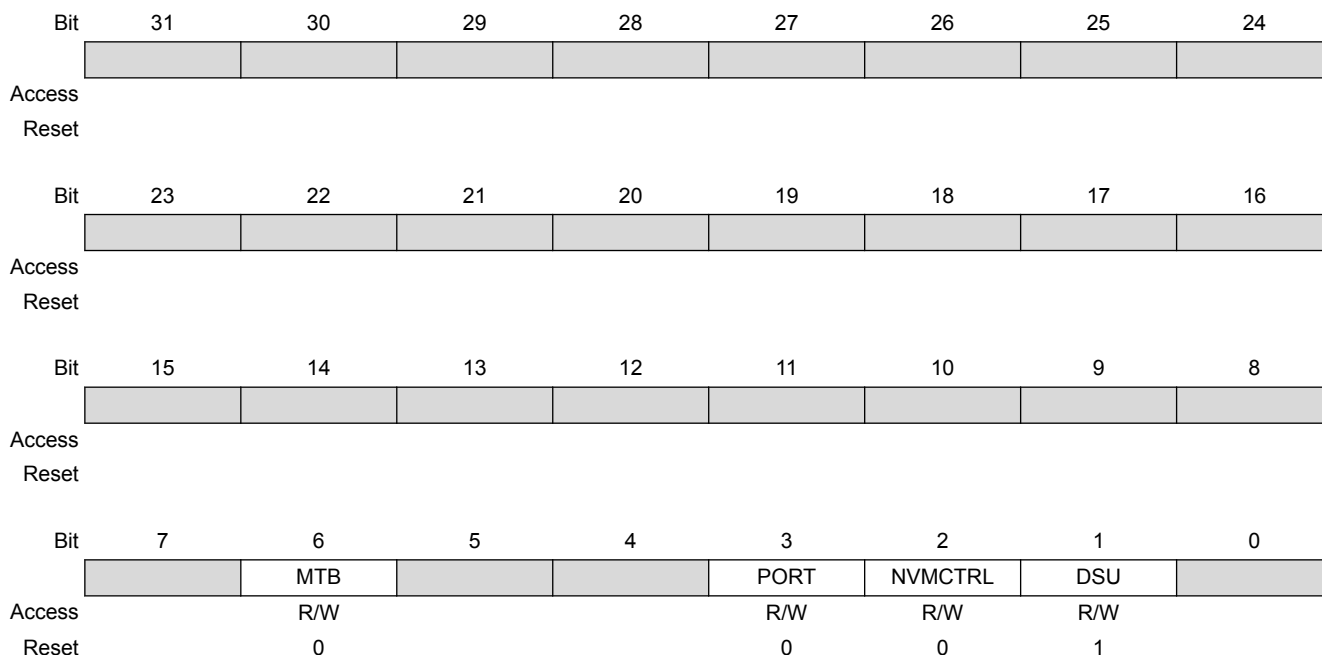
#### Bit 4 – WDT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

### 7.7.2.1. Write Protect Clear

**Name:** WPCLR  
**Offset:** 0x00  
**Reset:** 0x000002  
**Property:** –



#### Bit 6 – MTB

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 3 – PORT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 2 – NVMCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

### 7.7.2.2. Write Protect Set

**Name:** WPSET  
**Offset:** 0x04  
**Reset:** 0x000002  
**Property:** –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								
Bit	23	22	21	20	19	18	17	16
Access								
Reset								
Bit	15	14	13	12	11	10	9	8
Access								
Reset								
Bit	7	6	5	4	3	2	1	0
		MTB			PORT	NVMCTRL	DSU	
Access		R/W			R/W	R/W	R/W	
Reset		0			0	0	1	

#### Bit 6 – MTB

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 3 – PORT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 2 – NVMCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 1 – DSU

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

### 7.7.3. PAC2 Register Description

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 16 – ADC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bits 15,14,13,12,11,10,9,8 – TCx

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bits 7,6,5,4,3,2 – SERCOMx

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

#### Bit 1 – EVSYS

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

## 8. Packaging Information

### 8.1. Thermal Considerations

#### Related Links

[Junction Temperature](#) on page 39

#### 8.1.1. Thermal Resistance Data

The following *table* summarizes the thermal resistance data depending on the package.

**Table 8-1. Thermal Resistance Data**

Package Type	$\theta_{JA}$	$\theta_{JC}$
32-pin TQFP	68.0°C/W	25.8°C/W
48-pin TQFP	78.8°C/W	12.3°C/W
64-pin TQFP	66.7°C/W	11.9°C/W
32-pin QFN	37.2°C/W	13.1°C/W
48-pin QFN	33.0°C/W	11.4°C/W
64-pin QFN	33.5°C/W	11.2°C/W
64-ball UFBGA	67.4°C/W	12.4°C/W
45-ball WLCSP	37.0°C/W	0.36°C/W

#### 8.1.2. Junction Temperature

The average chip-junction temperature,  $T_J$ , in °C can be obtained from the following:

1.  $T_J = T_A + (P_D \times \theta_{JA})$
2.  $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- $\theta_{JA}$  = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- $\theta_{JC}$  = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$  = Thermal resistance (°C/W) specification of the external cooling device
- $P_D$  = Device power consumption (W)
- $T_A$  = Ambient temperature (°C)

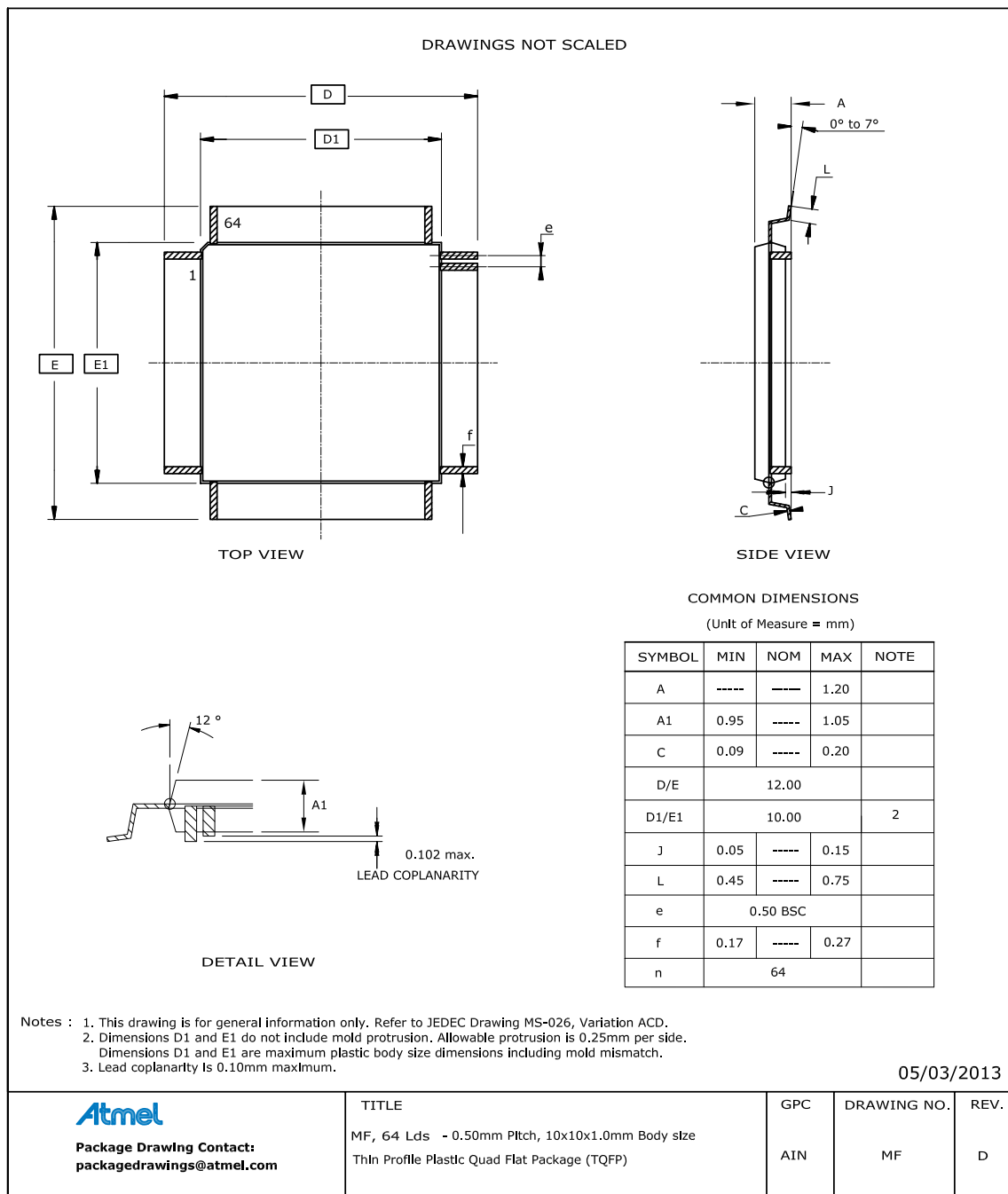
From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature  $T_J$  in °C.

#### Related Links

[Thermal Considerations](#) on page 39

## 8.2. Package Drawings

### 8.2.1. 64 pin TQFP



**Table 8-2. Device and Package Maximum Weight**

300	mg
-----	----

**Table 8-3. Package Characteristics**

Moisture Sensitivity Level	MSL3
----------------------------	------

**Table 8-11. Device and Package Maximum Weight**

140	mg
-----	----

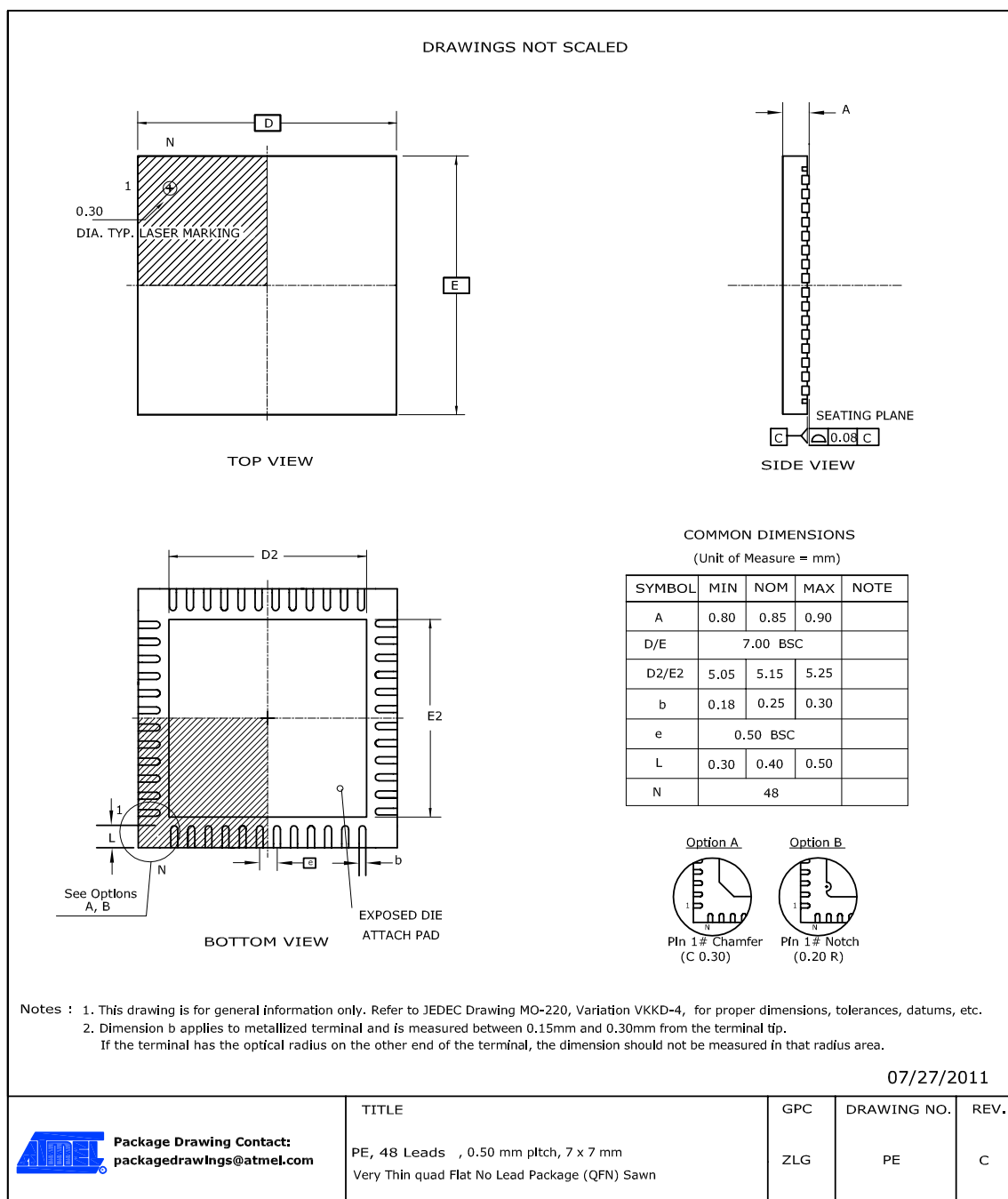
**Table 8-12. Package Characteristics**

Moisture Sensitivity Level	MSL3
----------------------------	------

**Table 8-13. Package Reference**

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

## 8.2.5. 48 pin QFN



**Note:** The exposed die attach pad is not connected electrically inside the device.

**Table 8-14. Device and Package Maximum Weight**

140	mg
-----	----

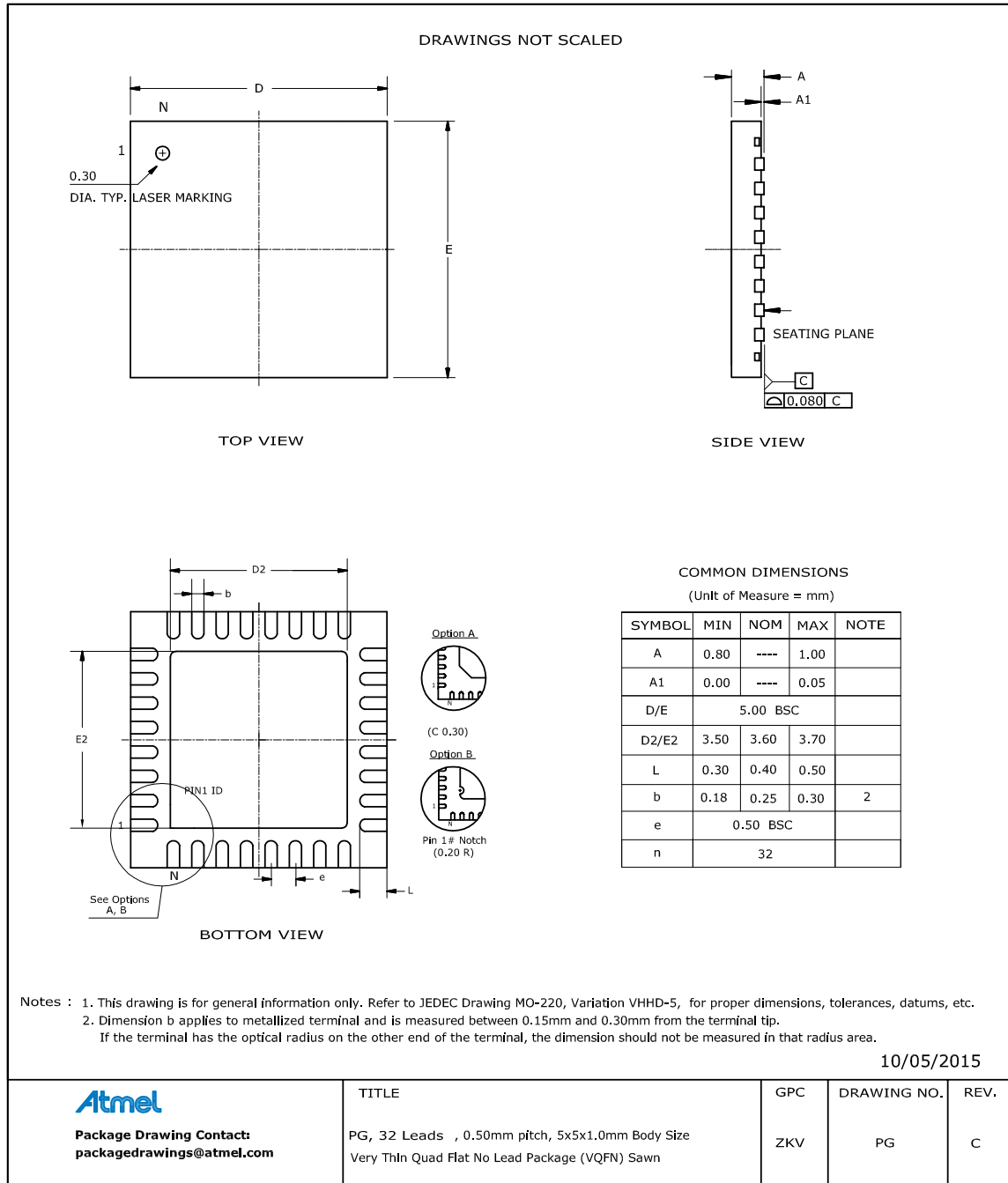
**Table 8-15. Package Characteristics**

Moisture Sensitivity Level	MSL3
----------------------------	------

**Table 8-22. Package Reference**

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

### 8.2.8. 32 pin QFN



**Note:** The exposed die attach pad is connected inside the device to GND and GNDANA.

**Table 8-23. Device and Package Maximum Weight**

90	mg
----	----

**Table 8-27. Package Characteristics**

Moisture Sensitivity Level	MSL1
----------------------------	------

**Table 8-28. Package Reference**

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

### 8.3. Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

**Table 8-29.**

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.